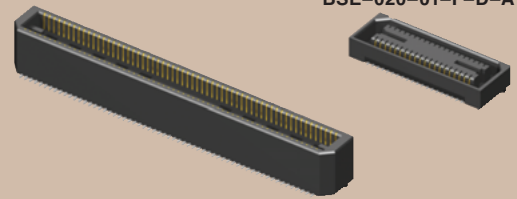


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BTE, BSE SERIES

(0,80 mm) .0315"

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2 A per pin (1 pin powered per row)
Operating Temp Range: -55°C to +125°C
Voltage Rating: 225 VAC with 5 mm Stack Height
Max Cycles: 100
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (020-080) (0,15 mm) .006" max (100-120)
Board Stacking:
 For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197
-02	(8,00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Edge Mount Capability
 - Friction Lock option
 - 11 mm, 14 mm, 16,10 mm, 19,10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE

NO. OF POSITIONS PER ROW

LEAD STYLE

PLATING OPTION

D

A

OTHER OPTION

Mates with: BSE

-020, -040, -060, -080, -100, -120

Specify LEAD STYLE from chart

LEAD STYLE	A
-01	(4,27) .168
-02	(7,21) .284

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K
= (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (60 positions maximum)

***Note:** -C Plating passes 10 year MFG testing

• Passes 10 year MFG

No. of positions x (0,80) .0315 + (4,00) .1575

(3,94) .155 (5,97) .235

(0,20) .008

(7,11) .280 (0,76) .030

(0,89) .035 DIA

BSE

NO. OF POSITIONS PER ROW

01

PLATING OPTION

D

A

OTHER OPTION

Mates with: BTE

-020, -040, -060, -080, -100, -120

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-TR
= Tape & Reel (80 positions maximum)

***Note:** -C Plating passes 10 year MFG testing

No. of positions x (0,80) .0315 + (5,27) .2075

(6,22) .245 (3,81) (7,24) .150 .285

(3,25) .128 (7,49) .295 (0,76) .030

(1,78) .070 (0,89) .035 DIA

Due to technical progress, all designs, specifications and components are subject to change without notice.